505455871 05/01/2019

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
CYPRIAN EMEKA UZOH	04/30/2019
JEREMY ALFRED THEIL	04/24/2019
LIANG WANG	04/24/2019
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GUILIAN GAO	04/24/2019
LAURA WILLS MIRKARIMI	04/30/2019

RECEIVING PARTY DATA

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Postal Code:	95134	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16363894

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ATTORNEY DOCKET NUMBER:	ZP146-0045-US-02	
NAME OF SUBMITTER:	CHRISTOPHER W. LATTIN	
SIGNATURE:	/Christopher W. Lattin/	
DATE SIGNED:	05/01/2019	
	This document serves as an Oath/Declaration (37 CFR 1.63).	

PATENT REEL: 049053 FRAME: 0327

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Total Attachments: 2

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> PATENT REEL: 049053 FRAME: 0328

COMBINED DECLARATION UNDER 37 CFR 1.63 AND ASSIGNMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, an ASSIGNOR named below,

Cyprian Emeka UZOH of San Jose, California, US
Jeremy Alfred THEIL of Mountain View, California, US
Liang WANG of Newark, California, US
Rajesh KATKAR of Milpitas, California, US
Guilian GAO of San Jose, California, US
Laura Wills MIRKARIMI of Sunol, California, US

hereby sell, assign and transfer to

ASSIGNEE:

ENTITLED:

	business at:	3025 Orchard Parkway,	, San Jose, CA 95134,
		resentatives, my entire rig , in and to the invention(s	ght, title and interest throughout the world, s) disclosed in:
\boxtimes	U.S. Patent Application	on executed on or about	t the date of this Assignment,
	U.S. Patent Application	on executed on	, or
\boxtimes	U.S. Patent Application	on No.: <u>16/363,894</u> , file	ed on March 25, 2019
	International Applicat	ion No.: PCT/	, filed on

Invensas Bonding Technologies, Inc., a Delaware corporation having a place of

and naming as

INVENTOR(S): Cyprian Emeka UZOH, Jeremy Alfred THEIL, Liang WANG, Rajesh KATKAR, Guilian GAO, Laura Wills MIRKARIMI

LOW TEMPERATURE BONDED STRUCTURES

including without limitation, my entire right, title and interest in and to any and all United States and foreign applications (including any and all provisional, international, regional and foreign national applications) for said invention(s), including non-provisionals, divisions, continuations, continuations-in-part, renewals, substitutes and extensions thereof, and in and to any and all patents of every country or region that may be granted or have been granted for said invention(s), including any reissues and reexaminations thereof.

Assignors hereby grant limited power of attorney to the attorneys/agents associated with Customer No. 79220 to update this document, as necessary, with an application number and a filing date for the above-referenced application.

OATH/DECLARATION

This Assignment may also serve as an oath or declaration in accord with 37 C.F.R. § 1.63(e) and, as such, as an inventor executing below, I do hereby state that I believe I am the original inventor or an original joint inventor of an invention claimed in any above-identified U.S. Patent Application or International Application designating the United States and do hereby state that such application is and was made or authorized to be made by me. I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

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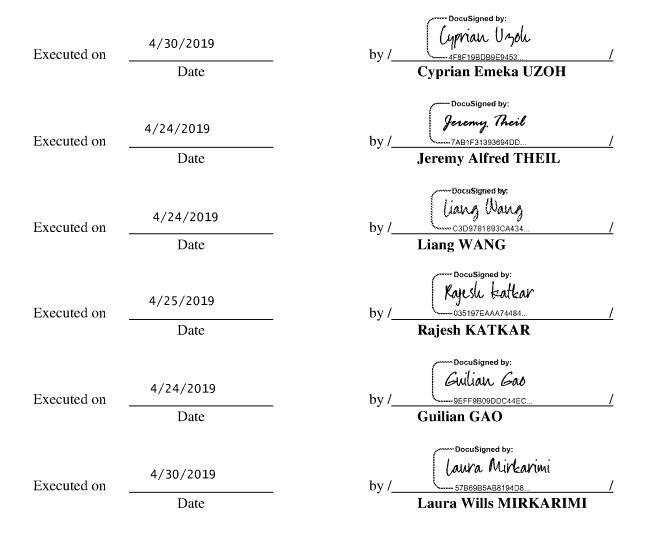
REEL: 049053 FRAME: 0329

I authorize ASSIGNEE to apply for patents of foreign countries for said invention(s), and to claim all rights of priority without further authorization from me.

I agree to execute any and all papers useful in connection with any and all U.S. and foreign applications (including international, regional, and foreign national applications), and generally to do everything possible to aid ASSIGNEE, its successors, assigns and nominees, at their request and reasonable expense, in obtaining and enforcing patents for said invention(s) in all countries.

I hereby covenant that no assignment, sale, license, agreement, or encumbrance has been or will be made or entered into that would conflict with this Assignment.

I authorize and request the Commissioner of Patents and Trademarks to issue any U.S. Letters Patent that may be granted for said invention(s) to ASSIGNEE, its successors or assigns.



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RECORDED: 05/01/2019

REEL: 049053 FRAME: 0330